

**ABSTRACT**

A radio frequency identification (RFID) device includes a conductive pattern, such as an antenna, on one side of a substrate, and a chip, such as part of a strap, electrically coupled to the conductive pattern, and either on an opposite side of the substrate or on the same side of the substrate as the antenna. A method of fabricating the RFID device may include crimping the strap onto the substrate, in contact with a seed layer, which is subsequently used in forming the antenna or other conductive pattern by plating. The seed layer may be a patterned conductive ink layer. Alternatively, the seed layer may be a layer of conductive material deposited on the substrate, such as by vacuum deposition. Parts of the deposited layer may be covered with a patterned mask in order to form the desired configuration of the conductive pattern.